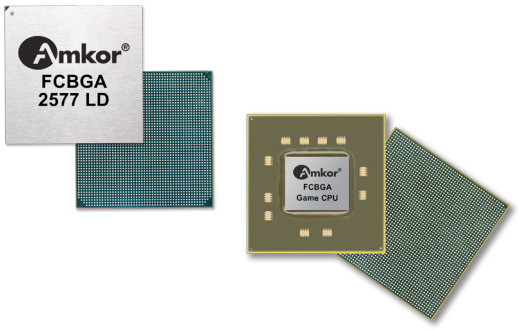


FCBGA

Flip Chip BGA Packages (FCBGA)

Flip chip interconnect utilizes array interconnect of die to substrate as a replacement for conventional wire bonding. This allows the entire die surface to be used for electrical connections to the substrate, exponentially increasing the I/O per unit area vs. perimeter interconnect technologies. Using flip chip interconnect improves package electrical performance by removing the high inductance wires and replacing them with low inductance solder connections. Flip chip interconnect also allows highly parallel, direct connection with on-die power planes, which enables performance at lower operating voltages.

Amkor FCBGA packages are assembled around state-of-the-art, single unit laminate or ceramic substrates. Utilizing multiple high density routing layers, laser drilled blind, buried, and stacked vias, and ultra fine line/space metallization, FCBGA substrates have the highest routing density available. By combining flip chip interconnect with ultra advanced substrate technology, FCBGA packages can be electrically tuned for maximum electrical performance. Once the electrical function is defined, the design flexibility enabled by flip chip also allows for significant options in final package design. Amkor offers FCBGA packaging in a variety of product formats to fit a wide range of end application requirements.

Applications

This IC packaging technology is applicable for high pincount and/or high performance ASICs. Large body FCBGAs provide package solutions for the demands of internet, workstation processors and high bandwidth system communication devices. By incorporating flip chip interconnect technology, packages supporting thousands of connections are enabled in conventional surface mount package sizes. FCBGAs are also the package of choice for gaming system processors and graphics, as well as high-end applications processors for leading-edge portable devices.

Features

- Die sizes up to 26 mm
- Package sizes from 10 mm to 55 mm (60 mm and 65 mm in development)
- 0.4 mm, 0.5 mm, 0.65 mm, 0.8 mm and 1.0 mm pitch BGA footprints
- 130 µm minimum array bump pitch
- < 100 µm minimum peripheral bump pitch

Technology Options

- Substrates
  - 4-16 layer laminate build up substrates
  - High CTE ceramic
  - LTCC alumina ceramic
  - Coreless
- Bump Types
  - Eutectic Sn/Pb
  - High Pb
  - Pb Free
  - Cu pillar (array and fine pitch peripheral)
- Package Formats
  - Bare die
  - Lidded

Thermal Solutions

The variety of FCBGA package options allows package selection to be tailored to the specific thermal needs of the end product. High performance ASIC products typically utilize a lidded format that features a controlled bondline die attach direct to a copper heat spreader. This feature produces the lowest possible thermal resistance (Theta JC) between the package and any externally applied thermal solution. The copper heat spreader effectively spreads heat laterally away from the die to the package perimeter and into the motherboard.

Lower wattage products generally utilize bare die or molded configurations. In these cases, the flip chip construction, with solder bumps and core vias, provides a lower resistance path from the active side of the die through the substrate, allowing heat dissipation both from the package surface and into the motherboard.

Visit Amkor Technology online for locations and to view the most current product information.

Data Sheet

FCBGA

Additional Package Options

- Wafer Node -≥ 28 nm qualified, 20 nm in development
- SMT components on top or bottom side
- Multi-die capability
- Memory components on top side
- Variety of lid material options
- Grounded lid
- Custom BGA footprints

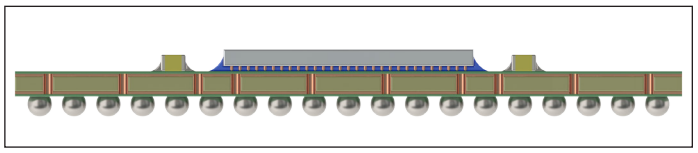
Test Services

- Program generation/conversion
- Product engineering
- Available test/handling technology
- Burn-in capabilities

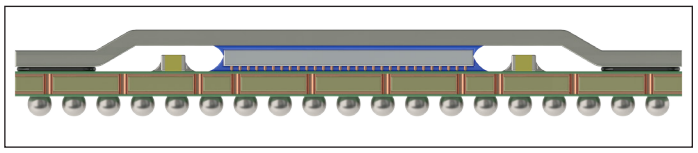
Shipping

- Standard JEDEC trays

Cross-section FCBGA



Bare Die FCBGA



Lidded FCBGA

Configuration Options

Full Array Ball Counts (Ball Count Shown Indicates Maximum Package Size Produced to Date)

Body Size	0.4 mm	0.5 mm	0.65 mm	0.8 mm	1 mm
	Ball Count	Ball Count	Ball Count	Ball Count	Ball Count
10	576	361	196	121	81
11	676	441	256	144	100
12	841	529	289	196	121
13	961	625	361	225	144
14	1156	729	400	256	169
15	1296	841	484	289	196
16	1521	961	529	361	225
17			625	400	256
19			784	484	324
21			961	625	400
23			1156	729	484
25			1369	900	576
27				1024	676
29				1225	784

Body Size	0.4 mm	0.5 mm	0.65 mm	0.8 mm	1 mm
	Ball Count	Ball Count	Ball Count	Ball Count	Ball Count
31				1369	900
33				1600	1024
35				1764	1156
37.5				2025	1296
40					1521
42.5					1681
45					1936
47.5					2116
50					2401
52.5					2601
55					2916
57.5					3136
60					3481
65					4096

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